

Amendments to the Claims:

This listing of claims will replace all prior versions, and listings, of claims in the application:

Listing of Claims:

Claims:

1. (Currently Amended) A method for manufacturing an electronic module, characterized by comprising:

- taking a sheet, which has a first (1a) and a second (1b) surface, and which sheet includes an insulating-material layer (1) between the first (1a) and the second (1b) surface, as well as a conductive layer (4) on at least the first surface (1a),
- making at least one recess (2) in the sheet (1) that extends through the second surface (1b) and the insulating-material layer (1) as far as the conductive layer (4) on the first surface (1a), which covers the recess (2) from the direction of the first surface (1a),
- taking a component (6) having a contact surface with contact areas or contact protrusions,
- placing the component (6) in the recess (2) with its contact surface facing the first surface (1a) and,
- attaching the component (6) to the conductive layer (4), which covers the recess (2) from the direction of the first surface (1a), by gluing with the aid of an electrically insulating adhesive, and
- forming a conductive pattern (14) from the conductive layer (4) covering the recess (2) and forming an electrical contact between the component and the conductive pattern by making feed-throughs, which connect[[s]] at least some of the contact areas or contact protrusions of the component (6) electrically to placed in the recess (2), the conductive pattern.

2. (Currently Amended) A method according to Claim 1, wherein the components (6) are placed facing both the first (1a) and second (1b) surface in the insulating-material layer (1) and electrical contacts are formed to the components (6) in such a way that at least some of the components are connected to the conductive layer (4) on the first surface (1a) and at least some to the conductive layer (4) on the second surface (1b).

3. (Currently Amended) A method according to Claim 1 or 2, comprising performing, after the component (6) or several components (6) have been attached to the conductive layer (4), which closes the recess (2) or recesses (2) from the direction of the first surface (1a), the following steps:

- making a conductive layer (9) on the second surface (1b) of the sheet,
- making at least one recess (2) in the sheet (1), which extends through the first surface (1a) and the insulating-material layer (1) as far as the conductive layer (9) on the second surface (1b), which covers the recess (2) from the direction of the second surface (1b),
- taking a component (6) having a contact surface with contact areas or contact protrusions,
- placing the component (6) in the recess (2), with its contact surface towards the second surface (1b) and attaching the component (6) to the conductive layer (4), which covers the recess (2) from the direction of the second surface (1b), and
- forming a conductive pattern (19) from the conductive layer (9) covering the recess (2), which pattern is connected electrically to at least some of the contact areas or contact protrusions of the component (6) placed in the recess (2).

4. (Currently Amended) A method according to Claim 1 or 2, wherein said [[a]] sheet is a used sheet[[,]] which is surfaced with a conductive layer (4) on both surfaces, and in which the method comprises:

- manufacturing at least one second recess (2) is manufactured in the sheet (1), and extends the at least one second recess extending through the first surface

(1a) and the insulating-material layer (1) as far as the conductive layer (4) on the second surface (1b), which covers the manufactured recess (2) from the direction of the second surface (1b),

- taking a component (6) ~~is taken~~, which has a contact surface with contact areas or contact protrusions,
- placing the component (6) ~~is placed~~ in the recess (2) with its contact surface facing the second surface (1b) and attaching the component (6) ~~is attached~~ to the conductive layer (4), which covers the recess (2) from the direction of the second surface (1b), and
- forming a conductive pattern (14) ~~is formed~~ from the conductive layer (4) covering the recess (2), which pattern is electrically connected to at least some of the contact areas or contact protrusions of the component (6) set in the recess (2).

5. (Currently Amended) A method according to Claim 1 ~~or 2~~, wherein the thickness of the insulating-material layer (1) is less than the thickness of at least one component (6) attached to the conductive layer and in which the method comprises:

- taking at [[a]] least one second insulating-material sheet (11) ~~is taken~~,
- making in the second insulating-material sheet (11) at least one recess (2) for the said at least one component (6) attached to the conductive layer (4) ~~is made~~, and
- attaching the second insulating-material sheet (11) ~~is attached~~ to the first insulating-material layer (1) from the direction of the second surface (1b).

6. (Currently Amended) A method according to Claim 1, 2, ~~or 5~~, wherein a first and a second element are manufactured, both of which include an insulating-material layer (1), a conductive layer (4) on at least the first surface (1a) of the insulating-material layer (1), and at least one component (6) in at least one recess (2), and in which method comprises:

- taking at least one second insulating-material sheet (II) ~~is taken~~, and
- attaching the first and the second elements ~~are attached~~ to each other with the aid of the said second insulating-material sheet (II), in such a way that the second surfaces (Ib) of the insulating-material layers (I) contained in the elements face towards each other.

7. (Currently Amended) A method according to Claim[[s]] 5 or 6, wherein the first insulating-material layer (I) is of a first insulating material and the second insulating-material sheet (II) is of a second insulating material, which differs from the first insulating material.

8. (Cancelled).

9. (Cancelled).

10. (Currently Amended) A method according to ~~any of~~ Claim[[s]] 1 [[- 7]], wherein at least one component (6) is attached, and electrical contact with the conductive layer (4; 9) is formed by bonding the contact areas metallurgically to the conductive layer (4; 9), either directly, or through intermediary contact protrusions.

11. (Currently Amended) A method according to ~~any of~~ Claim[[s]] 1 [[- 10]], wherein at least one component (6) attached to the conductive layer (4; 9) is an unpacked microcircuit chip.

12. (Currently Amended) A method according to ~~any of~~ Claim[[s]] 1 [[- 11]], wherein, in order to create a multi-layer circuit-board structure, additional insulating layers and conductive layers are manufactured on the first (Ia) and/or the second (Ib) surface.

13. (Currently Amended) A method according to ~~any of~~ Claim[[s]] 1 [[- 12]], wherein the components (6) are embedded in at least two sheets (I), which are subsequently attached on top of each other.

14. (Currently Amended) A method according to ~~any of~~ Claim[[s]] 1 [[- 13]], wherein a conductive-pattern layer (14; 19) is manufactured on both the first (1a) and the second (1b) surfaces of the insulating-material layer (1).